

## 1. General description

Planar passivated sensitive gate four quadrant triac in an internally insulated ITO220 plastic package intended for use in general purpose bidirectional switching and phase control applications. This sensitive gate "series E" triac can be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits. The internally insulated mounting base gives good thermal performance combined with ease of handling and assembly by the user.

## 2. Features and benefits

- 2500 V RMS isolation voltage capability
- Direct interfacing to logic level ICs
- Direct interfacing to low power gate drivers and microcontrollers
- High blocking voltage capability
- Industry standard TO220 package for ease of handling
- Isolated mounting base
- Planar passivated for voltage ruggedness and reliability
- Sensitive gate
- Triggering in all four quadrants

## 3. Applications

- 230 V lamp dimmers
- General purpose switching and phase control

## 4. Quick reference data

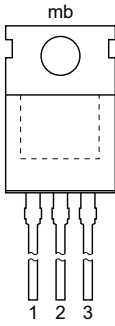
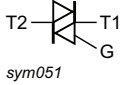
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DRM}$	repetitive peak off-state voltage		-	-	600	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 85\text{ °C}$ ; <a href="#">Fig.1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	-	-	12	A
$I_{TSM}$	non-repetitive peak on-state current	full sine wave; $T_{J(init)} = 25\text{ °C}$ ; $t_p = 20\text{ ms}$ ; <a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a>	-	-	95	A
		full sine wave; $T_{J(init)} = 25\text{ °C}$ ; $t_p = 16.7\text{ ms}$	-	-	105	A
$T_j$	junction temperature		-	-	125	°C
<b>Static characteristics</b>						
$I_{GT}$	gate trigger current	$V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G+; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 7</a>	-	-	10	mA
		$V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G-; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 7</a>	-	-	10	mA
		$V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2- G-; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 7</a>	-	-	10	mA
		$V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2- G+; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 7</a>	-	-	25	mA

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_H$	holding current	$V_D = 12\text{ V}$ ; $T_J = 25\text{ °C}$ ; <a href="#">Fig. 9</a>	-	-	30	mA
$V_T$	on-state voltage	$I_T = 15\text{ A}$ ; $T_J = 25\text{ °C}$ ; <a href="#">Fig. 10</a>	-	1.4	1.65	V
<b>Dynamic characteristics</b>						
$dV_D/dt$	rate of rise of off-state voltage	$V_{DM} = 402\text{ V}$ ; $T_J = 125\text{ °C}$ ; ( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform; gate open circuit	-	50	-	V/ $\mu$ s

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1		
2	T2	main terminal 2		
3	G	gate		
mb	n.c.	mounting base; isolated		

## 6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BT138Y-600E	IITO220	BT138Y-600E,127	Tube	50	SOT78D (A)	10-July-2007
					IITO220P (P)	31-Mar-2023

## 7. Marking

Table 4. Marking codes

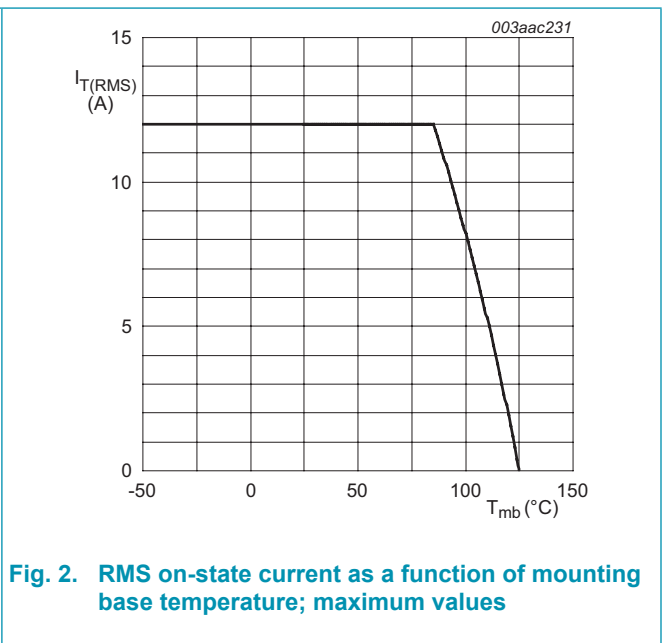
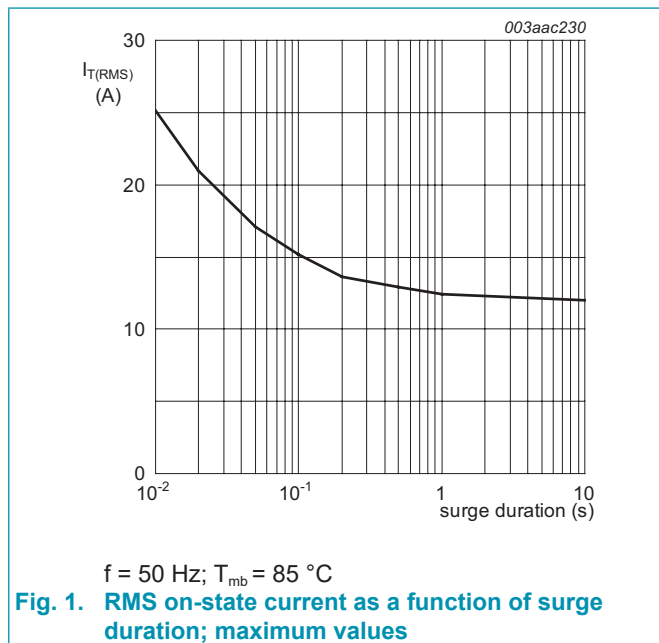
Type number	Marking codes	
	Assembly factory: A	Assembly factory: P
BT138Y-600E	BT138Y 600E PJAxxxx xx	BT138Y 600E PJPxxxx xx

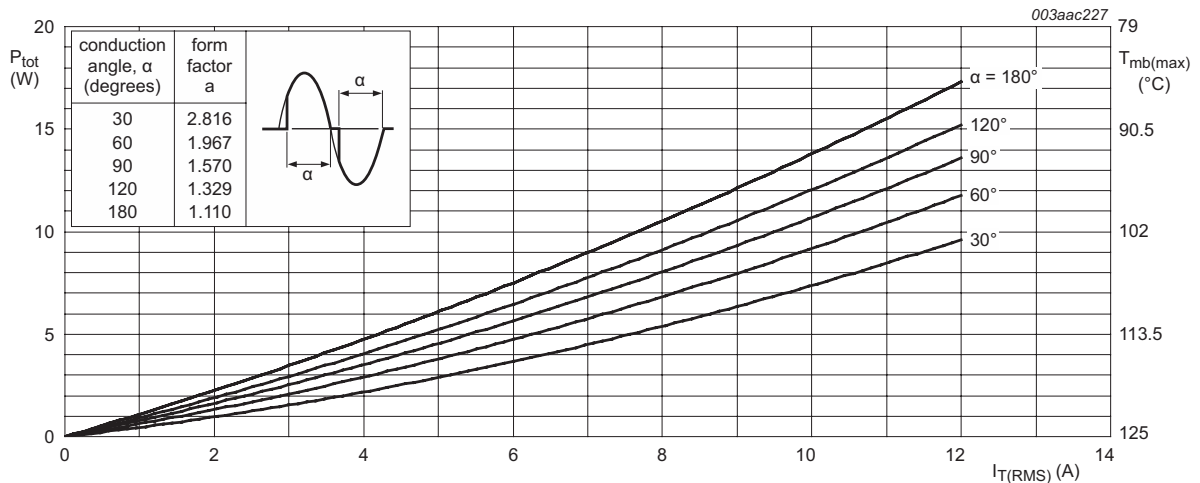
## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

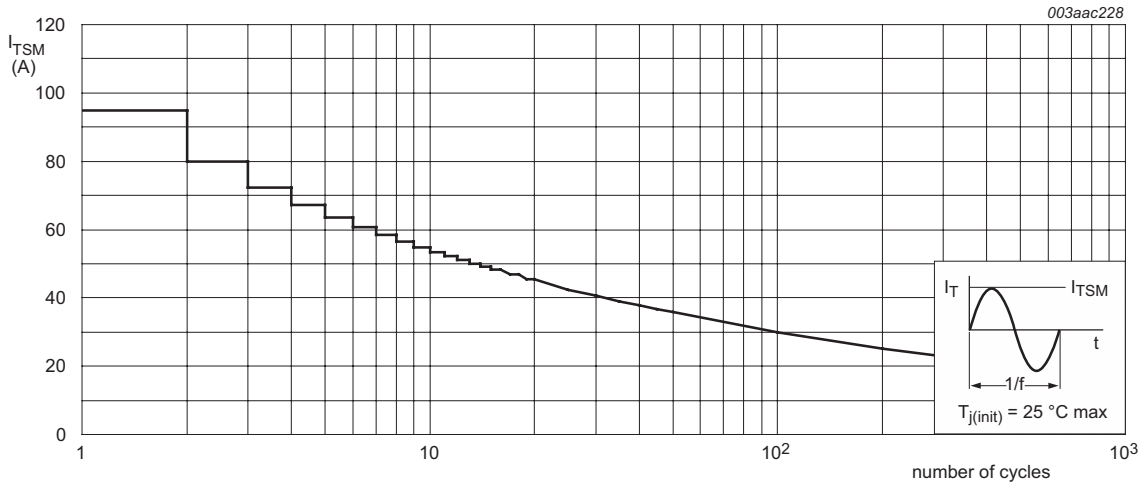
Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DRM}$	repetitive peak off-state voltage		-	600	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 85\text{ °C}$ ; <a href="#">Fig.1</a> ; <a href="#">Fig.2</a> ; <a href="#">Fig.3</a>	-	12	A
$I_{TSM}$	non-repetitive peak on-state current	full sine wave; $T_{j(\text{init})} = 25\text{ °C}$ ; $t_p = 20\text{ ms}$ ; <a href="#">Fig.4</a> ; <a href="#">Fig.5</a>	-	95	A
		full sine wave; $T_{j(\text{init})} = 25\text{ °C}$ ; $t_p = 16.7\text{ ms}$	-	105	A
$I^2t$	$I^2t$ for fusing	$t_p = 10\text{ ms}$ ; sine wave pulse	-	45	$A^2s$
$di_T/dt$	rate of rise of on-state current	$I_G = 100\text{ mA}$ ; T2+ G+	-	50	$A/\mu s$
		$I_G = 100\text{ mA}$ ; T2+ G-	-	50	$A/\mu s$
		$I_G = 100\text{ mA}$ ; T2- G-	-	50	$A/\mu s$
		$I_G = 100\text{ mA}$ ; T2- G+	-	10	$A/\mu s$
$I_{GM}$	peak gate current		-	2	A
$P_{GM}$	peak gate power		-	5	W
$P_{G(AV)}$	average gate power	over any 20 ms period	-	0.5	W
$T_{stg}$	storage temperature		-40	150	$^{\circ}C$
$T_j$	junction temperature		-	125	$^{\circ}C$





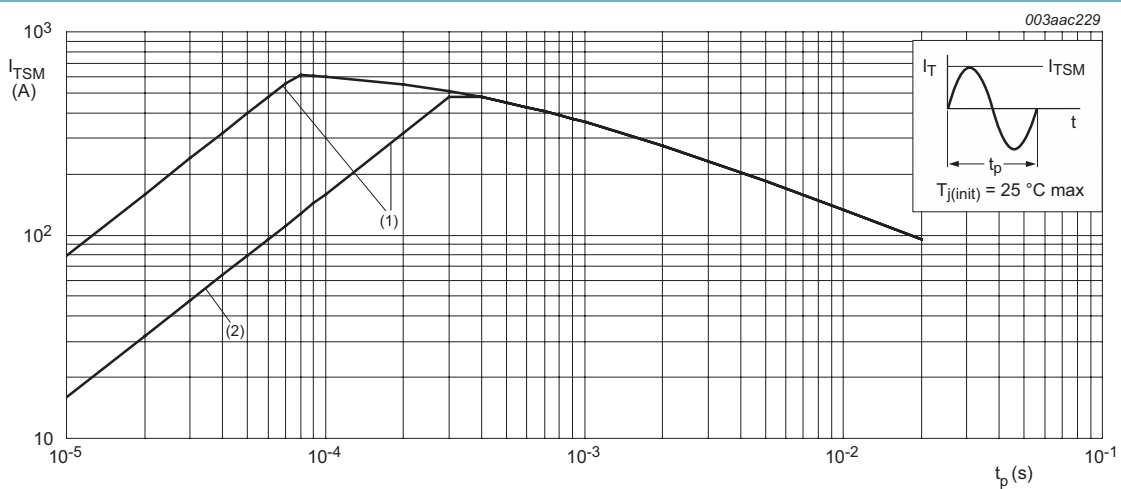
$a = \text{form factor} = I_{T(RMS)} / I_{T(AV)}$   
 $\alpha = \text{conduction angle}$

Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values



$f = 50 \text{ Hz}$

Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



$t_p \leq 20 \text{ ms}$   
 (1)  $di_T/dt$  limit    (2) T2- G+ quadrant limit

Fig. 5. Non-repetitive peak on-state current as a function of pulse duration; maximum values

## 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	full cycle; <a href="#">Fig. 6</a>	-	-	2.3	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	-	60	-	K/W

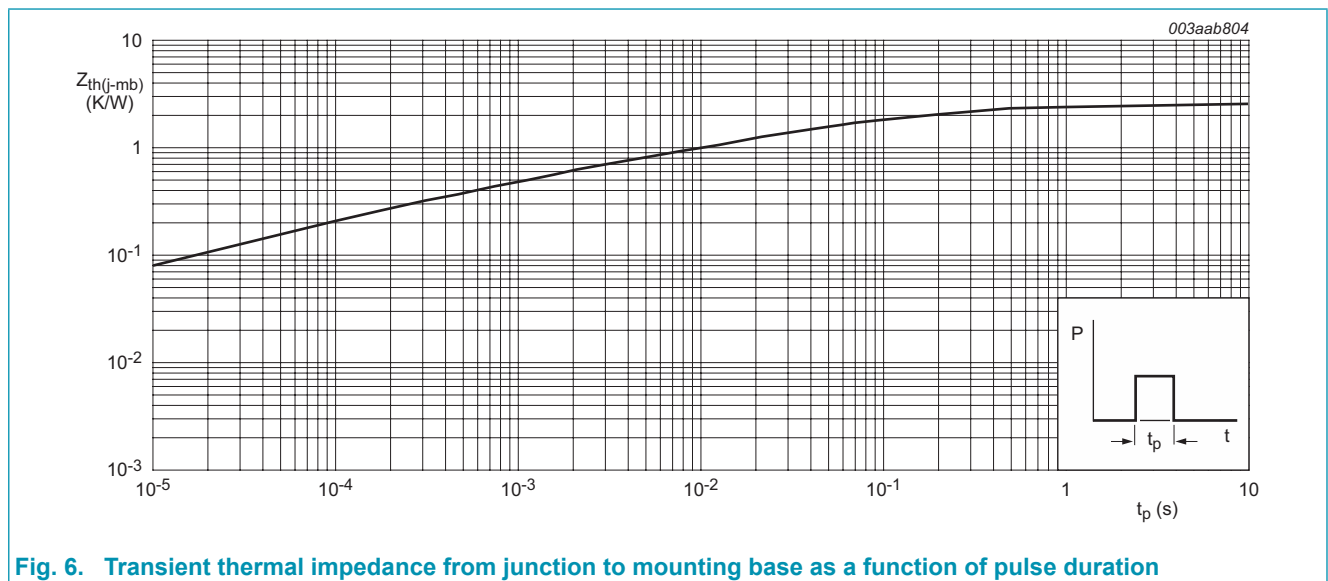


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse duration

## 10. Isolation characteristics

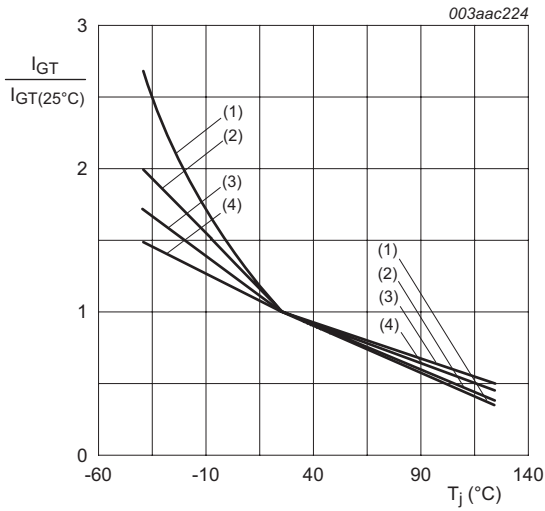
Table 7. Isolation Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{isol(RMS)}$	RMS isolation voltage	50 Hz ≤ f ≤ 60 Hz; RH ≤ 65 %; from all pins to external heatsink; sinusoidal waveform; clean and dust free	-	-	2500	V
$C_{isol}$	isolation capacitance	from cathode to external heatsink	-	10	-	pF

## 11. Characteristics

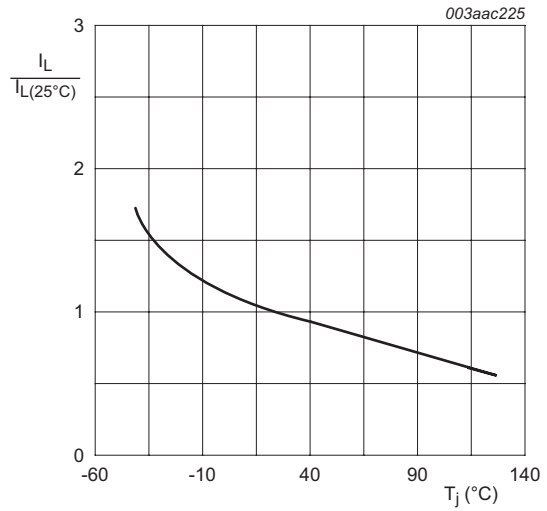
Table 8. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$I_{GT}$	gate trigger current	$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2+ G+;$ $T_j = 25\text{ °C};$ <a href="#">Fig. 7</a>	-	-	10	mA
		$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2+ G-;$ $T_j = 25\text{ °C};$ <a href="#">Fig. 7</a>	-	-	10	mA
		$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2- G-;$ $T_j = 25\text{ °C};$ <a href="#">Fig. 7</a>	-	-	10	mA
		$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2- G+;$ $T_j = 25\text{ °C};$ <a href="#">Fig. 7</a>	-	-	25	mA
$I_L$	latching current	$V_D = 12\text{ V}; I_G = 0.1\text{ A}; T_2+ G+;$ $T_j = 25\text{ °C};$ <a href="#">Fig. 8</a>	-	-	30	mA
		$V_D = 12\text{ V}; I_G = 0.1\text{ A}; T_2+ G-;$ $T_j = 25\text{ °C};$ <a href="#">Fig. 8</a>	-	-	40	mA
		$V_D = 12\text{ V}; I_G = 0.1\text{ A}; T_2- G-;$ $T_j = 25\text{ °C};$ <a href="#">Fig. 8</a>	-	-	30	mA
		$V_D = 12\text{ V}; I_G = 0.1\text{ A}; T_2- G+;$ $T_j = 25\text{ °C};$ <a href="#">Fig. 8</a>	-	-	40	mA
$I_H$	holding current	$V_D = 12\text{ V}; T_j = 25\text{ °C};$ <a href="#">Fig. 9</a>	-	-	30	mA
$V_T$	on-state voltage	$I_T = 15\text{ A}; T_j = 25\text{ °C};$ <a href="#">Fig. 10</a>	-	1.4	1.65	V
$V_{GT}$	gate trigger voltage	$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_j = 25\text{ °C}$ <a href="#">Fig. 11</a>	-	0.7	1	V
		$V_D = 600\text{ V}; I_T = 0.1\text{ A}; T_j = 150\text{ °C}$	0.25	0.4	-	V
$I_D$	off-state current	$V_D = 600\text{ V}; T_j = 125\text{ °C}$	-	0.1	0.5	$\mu\text{A}$
<b>Dynamic characteristics</b>						
$dV_D/dt$	rate of rise of off-state voltage	$V_{DM} = 402\text{ V}; T_j = 125\text{ °C}; (V_{DM} = 67\%$ of $V_{DRM});$ exponential waveform; gate open circuit	-	50	-	$\text{V}/\mu\text{s}$
$t_{gt}$	gate-controlled turn-on time	$I_{TM} = 16\text{ A}; V_D = 600\text{ V}; I_G = 100\text{ mA};$ $dI_G/dt = 5\text{ A}/\mu\text{s}$	-	2	-	A/ms

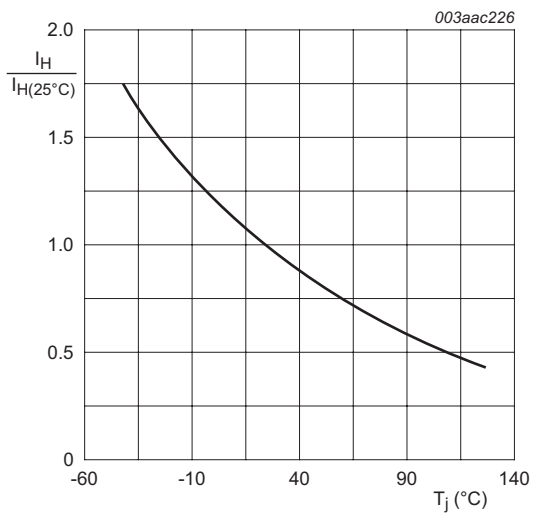


- (1) T2- G+
- (2) T2- G-
- (3) T2+ G-
- (4) T2+ G+

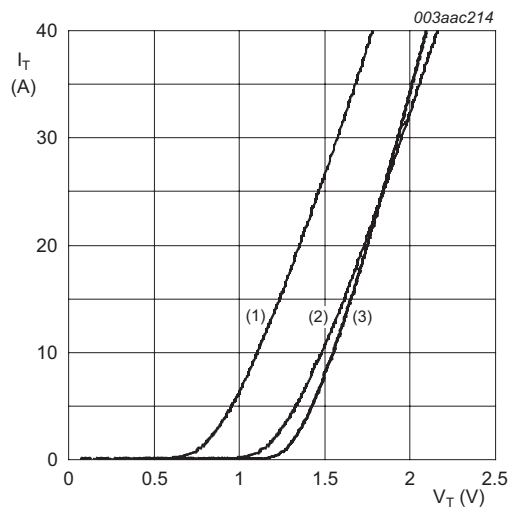
**Fig. 7. Normalized gate trigger current as a function of junction temperature**



**Fig. 8. Normalized latching current as a function of junction temperature**



**Fig. 9. Normalized holding current as a function of junction temperature**



- $V_o = 1.175 \text{ V}; R_s = 0.032 \Omega$
- (1)  $T_j = 125 \text{ }^\circ\text{C}$ ; typical values
  - (2)  $T_j = 125 \text{ }^\circ\text{C}$ ; maximum values
  - (3)  $T_j = 25 \text{ }^\circ\text{C}$ ; maximum values

**Fig. 10. On-state current as a function of on-state voltage**

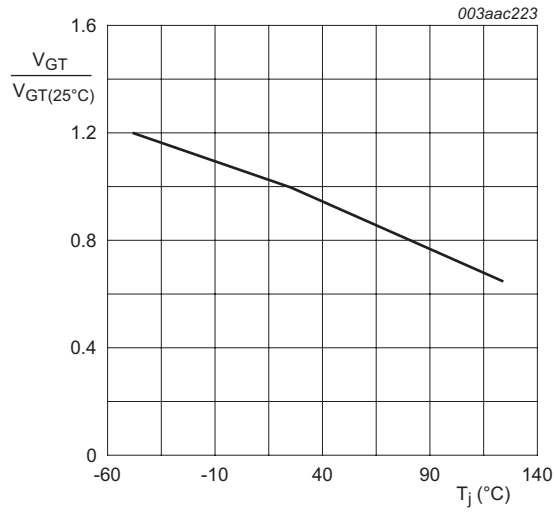


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

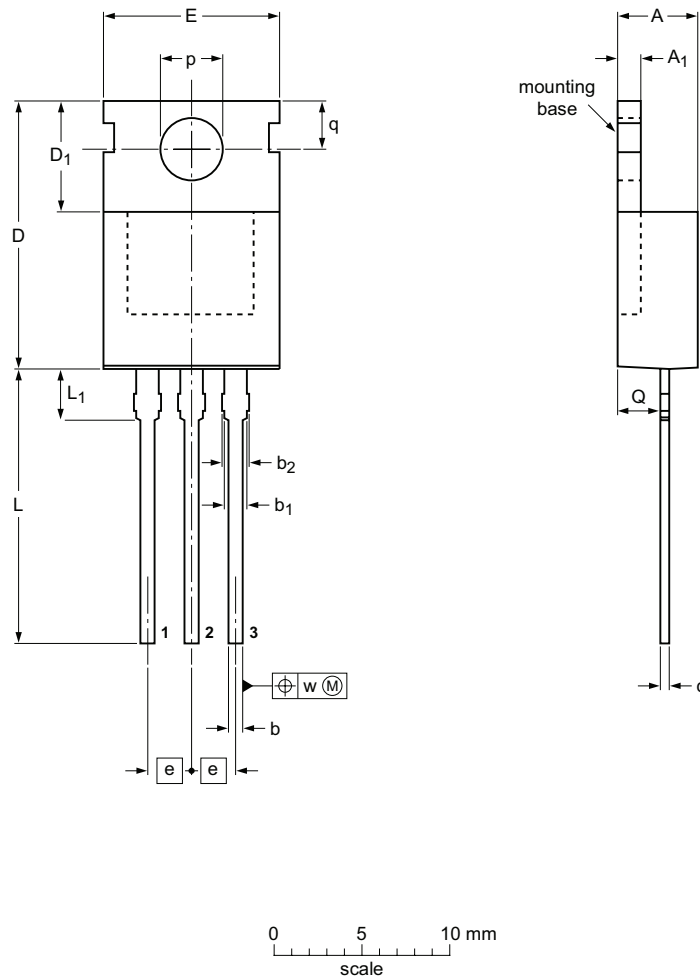


## 12. Package outline

Assembly factory: A

Plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-220

SOT78D



DIMENSIONS (mm are the original dimensions)

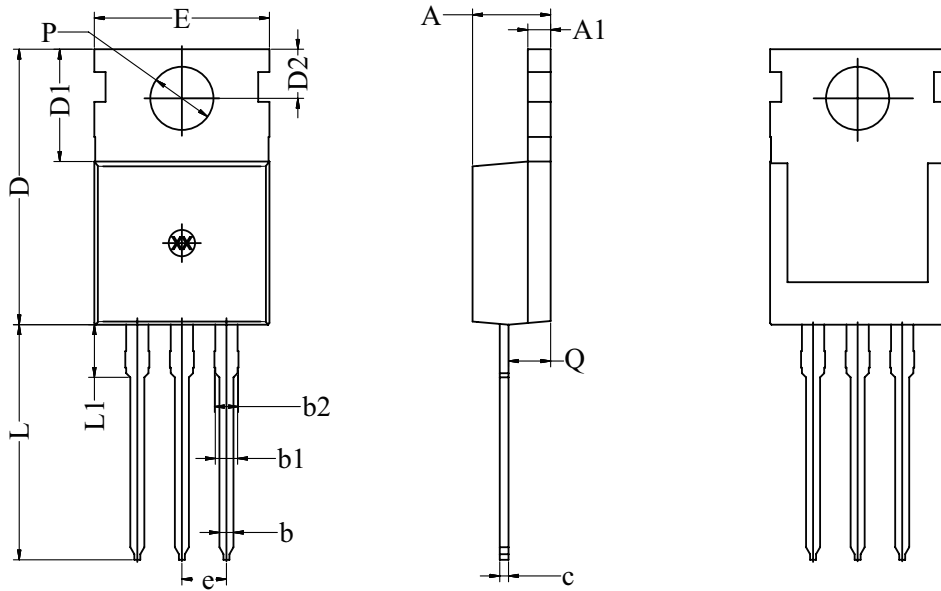
UNIT	A	A <sub>1</sub>	b	b <sub>1</sub>	b <sub>2</sub>	c	D	D <sub>1</sub> ref	E	e	L	L <sub>1</sub> ref	p	Q	q	w
mm	4.7 4.3	1.40 1.25	0.9 0.6	1.4 1.1	1.72 1.32	0.6 0.4	16.0 15.2	6.5	10.3 9.7	2.54	14.0 12.8	3.0	3.7 3.5	2.6 2.2	3.0 2.7	0.2

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT78D		TO-220			07-04-04 07-07-10

Assembly factory: P

Plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3 leads TO-220

IITO220



Dim	All Dimensions in Millimeters		
	Min	Typ	Max
A	4.30	4.45	4.70
A1	1.25	1.30	1.40
b	0.60	0.80	0.90
b1	1.10	1.27	1.40
b2	1.32	1.37	1.72
c	0.40	0.50	0.60
D	15.20	15.70	16.00
D1	6.20	6.40	6.60
D2	2.70	2.80	3.00
E	9.70	10.00	10.30
e	2.54 BSC		
L	12.80	13.40	14.00
L1	2.80	3.00	3.20
P	3.50	3.60	3.70
Q	2.20	2.40	2.60

## 13. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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